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Title of Change:	Update to FPCN23290X - SMAF Rectifiers Manufacturing Site Change.				
Proposed First Ship date:	29 Jul 2020 or earlier if approved by customer				
Contact Information:	Contact your local ON Semiconductor Sales Office or Benjo.Rulona@onsemi.com				
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>				
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or songyong.sim@onsemi.com				
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com				
Marking of Parts/ Traceability of Change:	Assembly Plant Code Marking Change from J to g				
Change Category:	Wafer Fab Change, Assembly Change				
Change Sub-Category(s):	Manufacturing Site Transfer				
Sites Affected:					

ON Semiconductor Sites	External Foundry/Subcon Sites
None	Good-Ark, China
	Panjit International Inc., Taiwan

Description and Purpose:

This is an Update Notification to FPCN23290X to include The POD Change and Package Outline Comparison Details as it was inadvertently excluded in the original PCN.

FPCN23290X was originally issued in April with details below:

As part of ON Semiconductor's effort to secure available capacity and meet customer's need of a reliable source for Rectifiers in SMAF package, qualification of Good-Ark located in Suzhou, China has been undertaken.

This new sourcing is intended to meet consistent supply and service and to prevent supply disruption to our customers.

These products are currently assembled and tested in a manufacturing site located in Taiwan. A comparison of the differences between the current and new sites' built parts are presented in the table below. Please note that there is also a slight change in the Package Outline Dimensions (POD):

	Before Change Description Afte		
Wafer Fab	Pynmax, Taiwan	Suzhou Good-Ark Electronics Co. Ltd	
Assembly Site	Panjit International Taiwan	Suzhou Good-Ark Electronics Co. Ltd	
Topmetal/Backmetal	Au	Ni	
Green Molding Compound	ELER-8-500C-S	EK1700GH/SP-G300	
POD Change	A	В	

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Final Product/Process Change Notification Document #:FPCN23290X1 Issue Date:15 Jun 2020

			From	า		То	
Produc	Product marking change		Assembly Plant Code J			Assembly Plant Code g	
kage Outline Di	mension Comparison		LΓ				
					•		
Package (mm) A	В	С	D	E	L	HE
Current (A)	0.9~1.1	1.60~1.9	0.1~0.25	2.3~2.7	3.6~4.0	0.5~0.95	4.4~5.0
New (B)	No Change	1.25~1.9	No Change	No Change	3.6~4.3	No Change	4.4~5.2
iability Data S	ummary:						
MS: SYSQR200	ME: QV-ES1JAF and E	S2DAF (QBS-ES					
V DEVICE NAI MS: SYSQR200	ME: QV-ES1JAF and E 0402	S2DAF (QBS-ES		Condition		Interval	Results
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA	ME: QV-ES1JAF and E 0402 F (DO-214AD)					Interval 1008 hrs	Results 0/240
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA	ME: QV-ES1JAF and E 0402 F (DO-214AD) Specification JESD22-A108 JESD22-A103		.0°C, 100% max r				
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA	ME: QV-ES1JAF and E 0402 F (DO-214AD) Specification JESD22-A108	Tj=15 Ta= 1 Ta=+2	.0°C, 100% max r	ated V		1008 hrs	0/240
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA Test HTRB HTRB	ME: QV-ES1JAF and E 0402 F (DO-214AD) Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037)	Tj=15 Ta= 1 Ta=+: On/o	0°C, 100% max r 50°C 25°C, delta Tj=100	ated V		1008 hrs 1008 hrs	0/240 0/240
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA Test HTRB HTSL IOL	ME: QV-ES1JAF and E 0402 F (DO-214AD) Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101	Tj=15 Ta= 1 Ta=+: On/o Ta=-:	0°C, 100% max r 50°C 25°C, delta Tj=100 ff = 2 min 55°C to +150°C	ated V		1008 hrs 1008 hrs 15000 cyc	0/240 0/240 0/120
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA Test HTRB HTRB HTSL IOL TC	ME: QV-ES1JAF and E 0402 F (DO-214AD) Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104	Tj=15 Ta= 1 Ta=+: On/o Ta= -: 130°C	0°C, 100% max r 50°C 25°C, delta Tj=100 ff = 2 min 55°C to +150°C	ated V D°C ig, bias 100V max		1008 hrs 1008 hrs 15000 cyc 1000 cyc	0/240 0/240 0/120 0/120
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA Test HTRB HTSL IOL TC HAST	ME: QV-ES1JAF and E 0402 F (DO-214AD)	Tj=15 Ta= 1 Ta=+: On/o Ta= -: 130°C 130°C	0°C, 100% max r 50°C 25°C, delta Tj=100 ff = 2 min 55°C to +150°C C, 85% RH, 18.8ps	ated V D°C ig, bias 100V max		1008 hrs 1008 hrs 15000 cyc 1000 cyc 96 hrs	0/240 0/240 0/120 0/120 0/120
V DEVICE NAI MS: SYSQR200 ACKAGE: SMA Test HTRB HTSL IOL TC HAST UHAST	ME: QV-ES1JAF and E 0402 F (DO-214AD) Specification JESD22-A108 JESD22-A103 MIL-STD-750 (M1037) AEC-Q101 JESD22-A104 JESD22-A110 JESD22-A118	Tj=15 Ta= 1 Ta=+: On/o Ta= -: 130°C 130°C	0°C, 100% max r 50°C 25°C, delta Tj=100 ff = 2 min 55°C to +150°C C, 85% RH, 18.8ps C, 85% RH, 18.8ps	ated V D°C ig, bias 100V max		1008 hrs 1008 hrs 15000 cyc 1000 cyc 96 hrs 96 hrs	0/240 0/240 0/120 0/120 0/120 0/120

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Electrical Characteristics Summary:

Electrical Characteristics as per datasheet specifications are not impacted. Parts covered in this change are expected to have comparable performance with the current parts in terms of quality and reliability.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
ES1DAF	ES1JAF
ES1JAF	ES1JAF
ES2DAF	ES2DAF

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
ES1DAF		ES1JAF	NA	
ES1JAF		ES1JAF	NA	
ES2DAF		ES2DAF	NA	